Process Fabrication for μDBS

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Abstract

The following content outlines the fabrication steps done in the Utah NanoFab Lab to build the μ DBS. The purpose of this lab is to establish working recipes for the process and keep track of past failures.

1 Design Process Overview

1.1 Design Architecture

The fabrication of the μ DBS begins with design in Cadence through the X-FAB XC06 design package. The design is sent to X-FAB Foundry (Erfurt, GE) for fabrication. The chips that are returned must undergo metal plating for the contacts and the bond pads, a parylene coating, dicing, wire bonding, and assembly. The design architecture can be found in Figure ??

1.2 Another subsection

For citing more than one paper, Please do like this [?,?,?]. If you want to cite only a few chapters of a book, please do like this [?, Chapters 1–3].

2 Creation of Gold Contacts

To refer a section, please use this: Section ??.

The equation can be done by:

$$a = b + c. (2.1)$$

Refer to the photo and equation can be done easily: Figure ?? and Equation ??.

You can also make a table like in Table ??:

A figure with two subfigures on its left and right sides can be done in, for example, Figure ??.

You can display any texts by:

\begin{figure} \centering
\end{figure}

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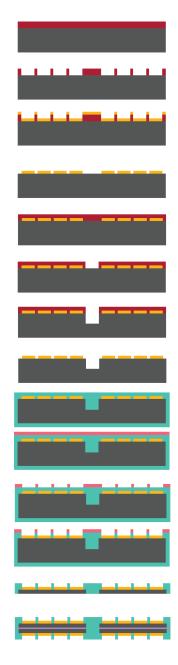


Figure 1.1: Design Architecture

Process	е
RPM	2000
Resist	1813

Table 2.1: This is a table.

Acknowledgments

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A Appendix 1

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